



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20160216000

**Qualify Hana Thailand (HNT) as an additional Assembly & Test site for select devices
Change Notification / Sample Request**

Date: 2/17/2016

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160216000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV70218DBVT	null
TLV70233DBVR	null
TLV70218DBVR	null
TLV70233DBVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160216000		PCN Date:	2/17/2016												
Title:	Qualify Hana Thailand (HNT) as an additional Assembly & Test site for select devices															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	5/17/2016	Estimated Sample Availability:	Provided upon Request													
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>												
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>												
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>												
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>												
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>												
		<input type="checkbox"/>	Part number change													
PCN Details																
Description of Change:																
Texas Instruments is pleased to announce the qualification of Hana Thailand (HNT) as an additional Assembly & Test site for the list of devices shown below. Construction differences between the 2 sites are as follows:																
<table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td>What</td> <td>NFME</td> <td>HNT</td> </tr> <tr> <td>Mount Compound</td> <td>SID# A-03</td> <td>SID#400154</td> </tr> </table>					What	NFME	HNT	Mount Compound	SID# A-03	SID#400154						
What	NFME	HNT														
Mount Compound	SID# A-03	SID#400154														
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																
Reason for Change:																
Continuity of Supply																
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																
None																
Anticipated impact on Material Declaration																
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .													
Changes to product identification resulting from this PCN:																
<table border="1" style="width: 100%;"> <tr> <td>Assembly Site</td> <td>Assembly Site Origin (22L)</td> <td>Assembly Country Code (21L)</td> <td>Assembly City</td> </tr> <tr> <td>NFME</td> <td>NFM</td> <td>CHN</td> <td>Economic Development Zone</td> </tr> <tr> <td>Hana Thailand</td> <td>HNT</td> <td>THA</td> <td>Ayutthaya</td> </tr> </table>					Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City	NFME	NFM	CHN	Economic Development Zone	Hana Thailand	HNT	THA	Ayutthaya
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City													
NFME	NFM	CHN	Economic Development Zone													
Hana Thailand	HNT	THA	Ayutthaya													
Sample product shipping label (not actual product label)																



MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM:

LBL: 5A (L)T0:1750



(1P) SN74LS07NSR

(Q) 2000 (D) 0336

(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2

(P)

(2P) REV: (V) 0033317

(20L) CS0: SHE (21L) CC0: USA

(22L) AS0: MLA (23L) AC0: MYS

Topside Device marking:

Assembly site code for NFM= E

Assembly site code for HNT = H

Product Affected

HPA01091DBVR	TLV70230DBVT	TLV70235DBVR	TLV70245DBVT
TLV70215DBVR	TLV70231DBVR	TLV70235DBVT	TLV702475DBVR
TLV70215DBVT	TLV70231DBVT	TLV70237DBVR	TLV702475DBVT
TLV70218DBVR	TLV70233DBVR	TLV70237DBVT	TLV71209DBVR
TLV70218DBVT	TLV70233DBVT	TLV70245DBVR	TLV71209DBVT
TLV70230DBVR			



TI Information
Selective Disclosure

Qualification Report

HNT AT Qualification (Qual Vehicle TLV70233DBV / RFAB/LBC7)

Product Attributes

Attributes	Qual Device: TLV70233DBV	QBS Product Reference: TLV70212DBV	QBS Product Reference: TLV70228PDBV	QBS Product Reference: TLV70248DBV	QBS Product Reference: TLV70248PDBV	QBS Product Reference: TLV71207DBV	QBS Product Reference: TLV71207PDBV
Die Attributes	-	-	-	-	-	-	-
Die Revision	A	A	A	A	A	A	A
Wafer Fab Supplier	RFAB	FFAB	FFAB	FFAB	FFAB	FFAB	FFAB
Wafer Process	LBC7	LBC7	LBC7	LBC7	LBC7	LBC7	LBC7
Assembly Site	HNT	HNT	HNT	HNT	HNT	HNT	HNT
Package Family	SOT23	SOT23	SOT23	SOT23	SOT23	SOT23	SOT23
Package Designator	DBV	DBV	DBV	DBV	DBV	DBV	DBV
Package Size (mils)	62.99 X 114.17	62.99 X 114.17	62.99 X 114.17	62.99 X 114.17	62.99 X 114.17	62.99 X 114.17	62.99 X 114.17
Body Thickness (mils)	57.09	57.09	57.09	57.09	57.09	57.09	57.09
Pin Count	5	5	5	5	5	5	5
Lead Frame Type	Cu	Cu	Cu	Cu	Cu	Cu	Cu
Lead Finish	NIPdAu	NIPdAu	NIPdAu	NIPdAu	NIPdAu	NIPdAu	NIPdAu
Lead Pitch (mils)	37.4	37.4	37.4	37.4	37.4	37.4	37.4

- QBS: Qual By Similarity

- Qual Device TLV70233DBV is qualified at LEVEL 1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV70233DBV	QBS Product Reference: TLV70212DBV	QBS Product Reference: TLV70228PDBV	QBS Product Reference: TLV70248DBV	QBS Product Reference: TLV70248PDBV	QBS Product Reference: TLV71207DBV	QBS Product Reference: TLV71207PDBV
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/10/0	1/10/0	1/10/0	1/30/0	1/10/0	1/10/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	-	-	-	-	-	-
HBM	ESD-HBM	3000 V	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0
CDM	ESD-CDM	1500 V	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0
HTOL	Life Test, 140C	324 Hours	-	-	-	-	-	-	-
HTOL	Life Test, 150C	300 Hours	3/231/0	-	-	-	-	-	-
HTSL	High Temp. Storage Bake, 160C	1000 Hours	3/231/0	-	-	-	-	-	-
LU	Latch-up (per JESD78)	-	-	-	-	1/6/0	1/6/0	1/6/0	1/6/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-	-	-	-	-	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	3/231/0	-	-	-	-	-	-
WBP	Bond Strength	Wires	3/228/0	-	-	1/76/0	1/76/0	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, Tri-Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7 eV: 125C/1k Hours, 140C/480 Hours, 150C/500 Hours, and 155C/240 Hours

- The following are equivalent HBM options based on an activation energy of 0.7 eV: 150C/1k Hours, and 1/10C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -65C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com